

A Conductance Technique for the Determination of Dopant Characteristics

C. R. Viswanathan, R. Divakaruni, J. Kizziar and V. Prabhakar
Electrical Engineering Department
UCLA, Los Angeles, California 90024

When semiconductor devices are operated at very low temperatures, the dopant atoms do not readily get ionized due to freeze-out effects. This causes a delay in the formation of the depletion region when the applied voltage is changed. This manifests itself as a transient in the drain current in MOS devices and a dispersion in CV curves in both field-effect and junction devices. In this paper, we report studies on dispersion effects in CV curves obtained on MOS transistors and p-n junction devices. The device behavior is modeled by an appropriate equivalent circuit. From the measured impedance of the device the conductance is obtained as a function of temperature and frequency. This enables the determination of emission time constant and the capture cross-section of the dopant atoms.

Impedance measurements were carried out on n-channel MOS transistors and p-n junction devices fabricated in a modern CMOS processing facility. The devices were mounted in a cold tip of a helium dewar whose temperature can be set to the desired value anywhere between room temperature and liquid helium temperature. Figure 1 gives the measured CV curves at different frequencies for the MOS transistor maintained at a temperature of 39 K. Similarly the dispersion observed in the p-n junction device at 36.8 K is shown in Figure 2. The long emission time constant of the dopant atoms causes a dispersion in the CV curves in both cases. The effect of the long emission time constant is modeled by the equivalent circuit shown in Figure 3 for the MOS device. The equivalent circuit for the p-n junction is similar except that the oxide capacitance is excluded. The measured impedance can be represented by a conductance G_p and a capacitance C.

The conductance was determined as a function of frequency and temperature. When the measured G_p/ω is plotted as a function of ω , a peak is observed at a value of ω equal to the reciprocal of the emission time constant. This is shown in Figure 4 for the MOS device and a similar behavior is obtained for the p-n junction although not shown here. In Figures 5 and 6, the reciprocal of the emission time constant is plotted as a function of the reciprocal temperature for the two devices. From the slope of the Arrhenius plot, the energy level of the dopant atoms and the capture cross-section are obtained. For the n-channel MOS transistor we obtain an energy of 39.5 meV and a capture cross-section of $7.68 \times 10^{-15} \text{ cm}^2$ for the acceptor atoms. Considering the p-n junction as an approximate one-sided junction we obtain corresponding values of 39.9 meV and $1.4 \times 10^{-14} \text{ cm}^2$ for the donor atoms. To conclude, it is shown in this study that the conductance technique at very low temperatures is a suitable technique for determining the emission time constant and the capture cross-section of the dopant atoms.

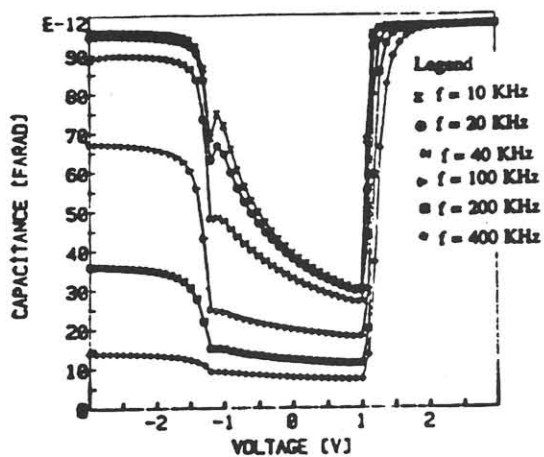


FIG. 1 C-V curves in a NMOS device at 39K

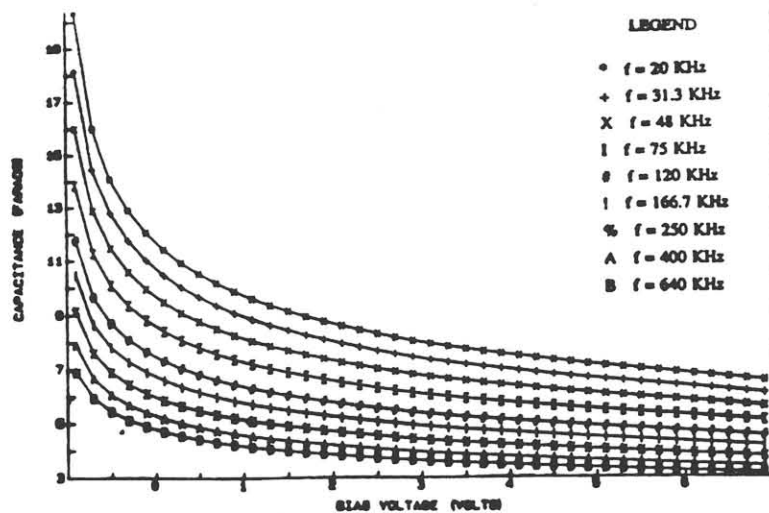


FIG. 2 C-V curves in a diode at 36.8 K

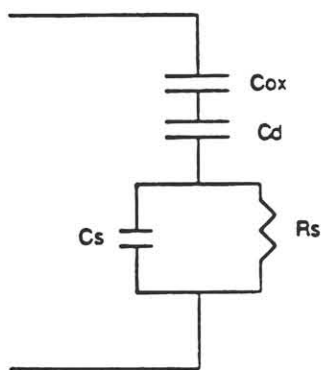


FIG. 3. EQUIVALENT CIRCUIT

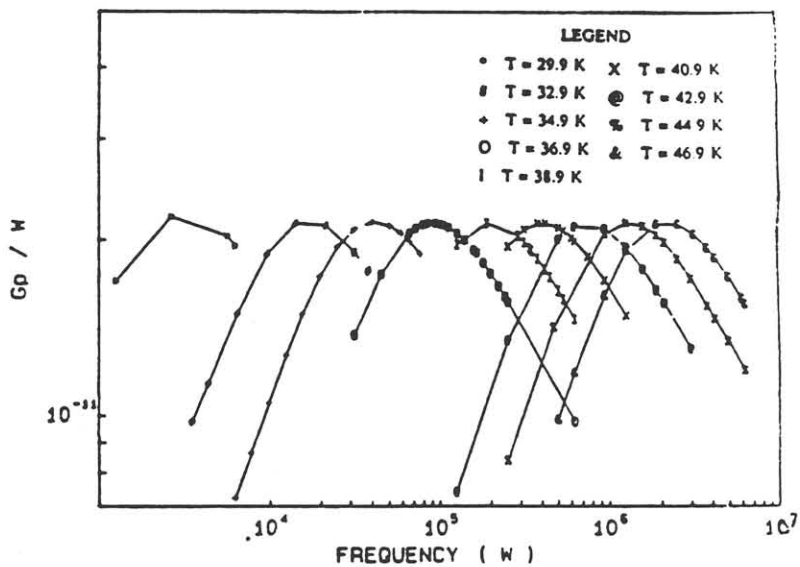


FIG. 4 G_p/ω vs. ω

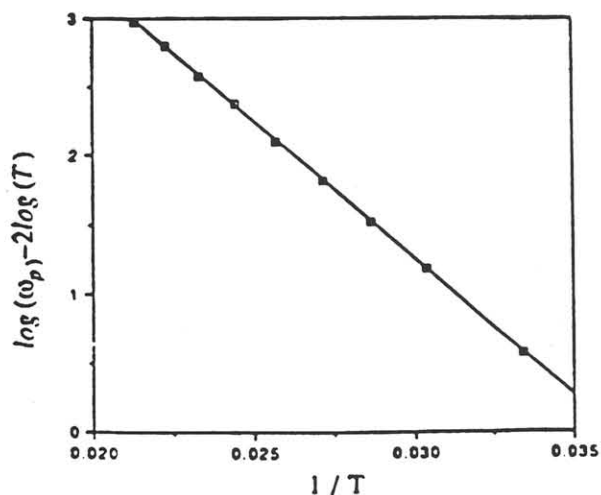


FIG. 5 ARRHENIUS PLOT ($E_a = 39.5\text{meV}$)

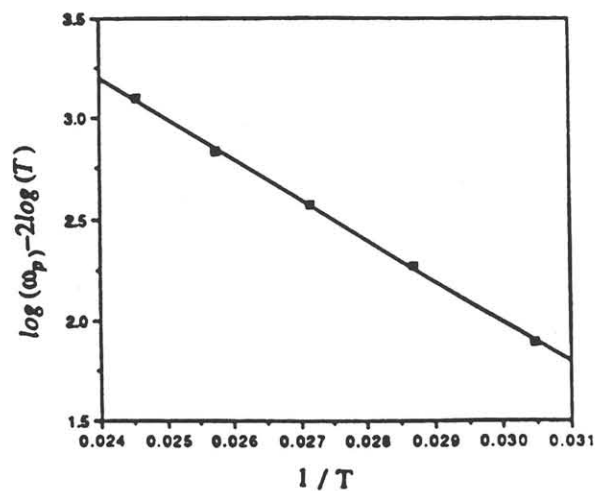


FIG. 6 ARRHENIUS PLOT ($E_a = 39.9\text{meV}$)